

POSITIONING APPARATUS AND METHOD

Abstract

Manufacturing of semiconductor devices is fully automated for cost savings to be achieved
5 in terms of capital and material costs. Semiconductor devices separated from the lead-
frames or substrates are typically washed and dried before being transferred to a plate. The
semiconductor devices are then subsequently transferred from the plate to a holding tray.
However, the large contact surface between the semiconductor devices and the plate results
10 in the semiconductor devices adhering to the surface of the plate when transferring the
semiconductor devices to the holding tray. Furthermore, misalignment also tends to occur
when the devices are transferred from the plate to the holding tray due to gravitational
displacement of the semiconductor devices occurring during the transfer. An embodiment of
the invention describes an apparatus and a method for transferring semiconductor devices
15 into component pockets of holding trays.

FIG. 6